

Description: 860-930MHz Embedded Helical Antenna

PART NUMBER: W3136

Series: SMD Helical Antenna





Features:

- 860-930MHz
- Impedance 50 Ohm
- · Plastic support helical antenna
- Size(helix): Length 29.5mm,
- Gain 1.5dBi
- SMD Mounting on PCB
- RoHS Compliant

Applications:

- 868MHz and 915MHz ISM Band Systems
- IoT systems
- Metering, Automation
- Security, surveillance
- · Remote controls, toys

All dimensions are in mm / inches

Issue: 1748

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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ELECTRICAL SPECIFICATIONS

Antenna Type	Helical
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Frequency 860-930MHz

Nominal Impedance 50 Ω

VSWR Max 2.5

Radiation Pattern Omni

Gain 2 dBi

Efficiency 50%

Polarization Linear

Power Withstanding 2W

MECHANICAL SPECIFICATIONS

Overall Length 29.5mm

Weight 2.52g

Antenna Color / Material White

Fix system SMD+Glue

Recommended Glue Resinlab EP1320LV Black

Solder Paste Thickness Min 0.15mm

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature -40° C~+85 ° C

Storage Temperature -40 ° C ~+85° C

RoHS Compliant Yes

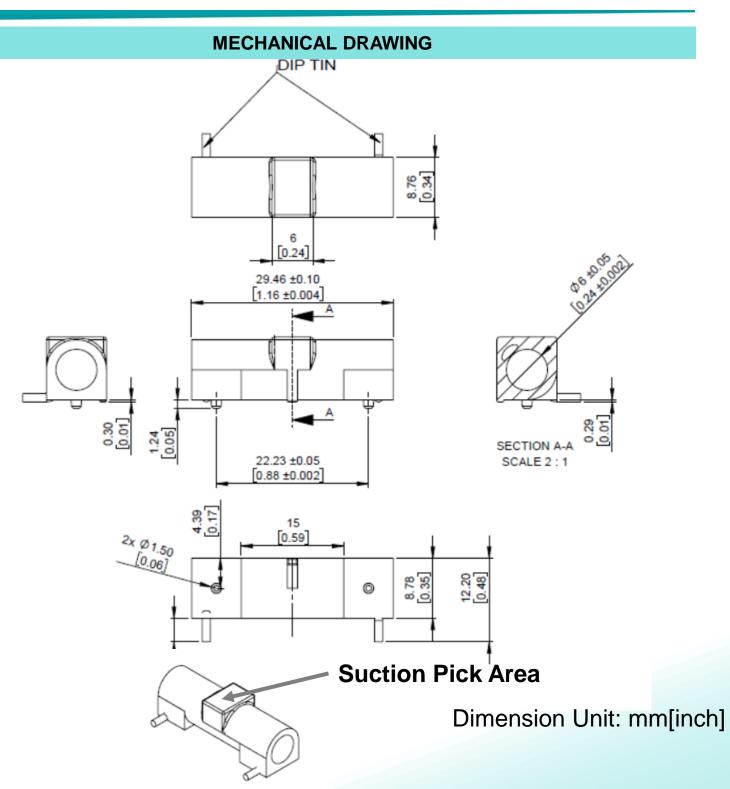
OTHER SPECIFICATIONS



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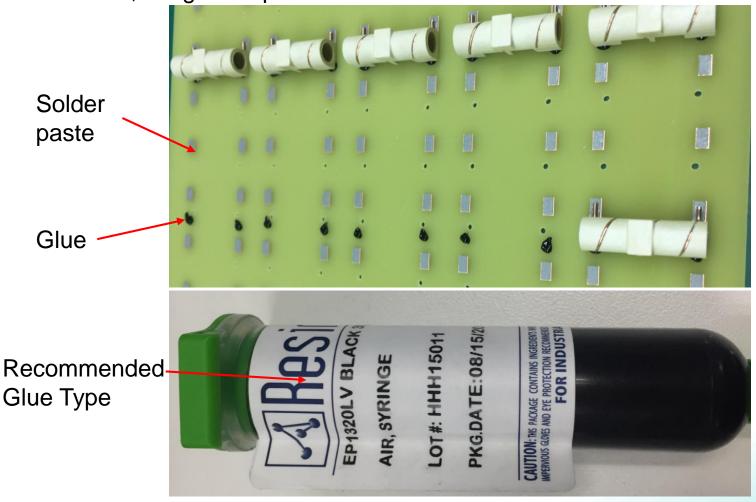
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FIX SYSTEM RECOMMENDATION

Fix system

- 1. SMD process
- 2. Solder paste thickness: minimum 0.15mm
- 3. Glue is required, Recommended Glue: Resinlab EP1320LV Black, usage and position see below recommended area.









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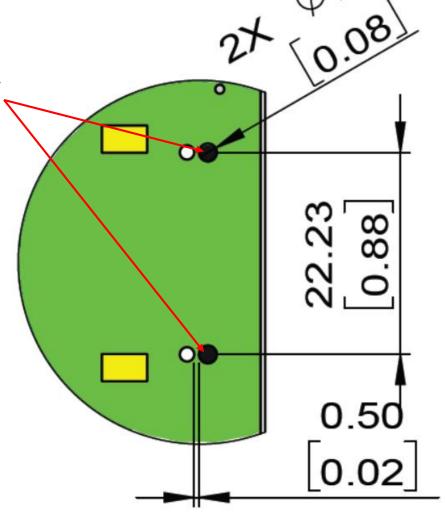
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FIX SYSTEM RECOMMENDATION

Fix system

1. Glue position on PCB for recommendation

Glue position on PCB for recommendation





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FIX SYSTEM RECOMMENDATION Solder effect Back view of glue area

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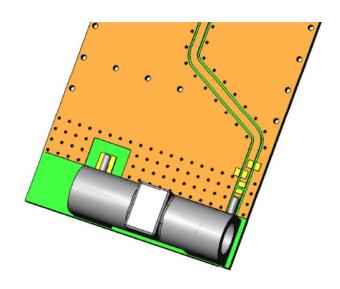
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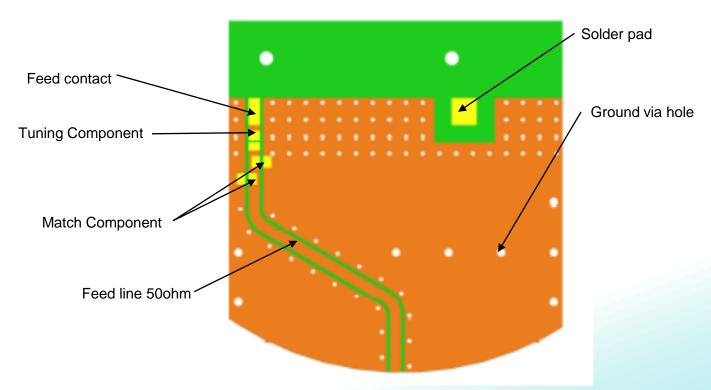
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TEST SETUP

PWB Layout for W3136 SMD Helical Antenna





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ROHS



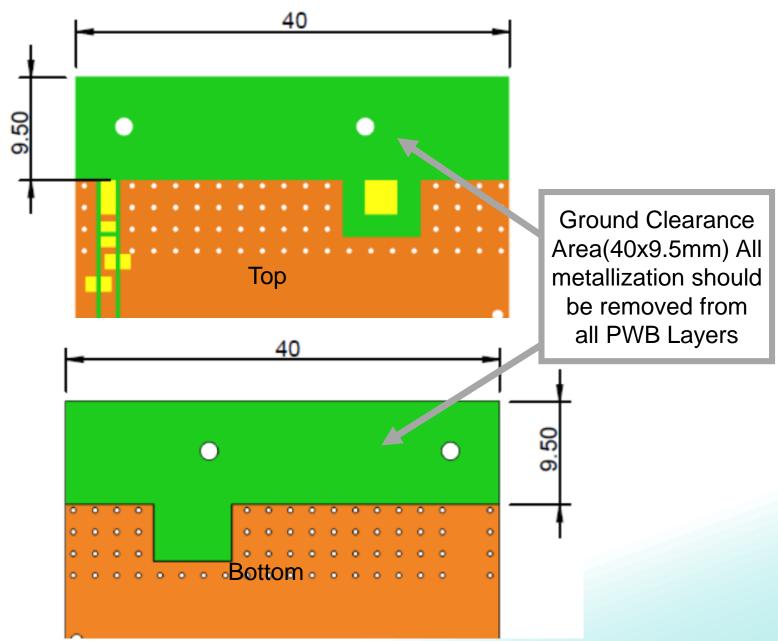
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PWB ground clearance area (Top):40x9.5mm PWB ground clearance area (Bottom):40x9.5mm



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ROHS



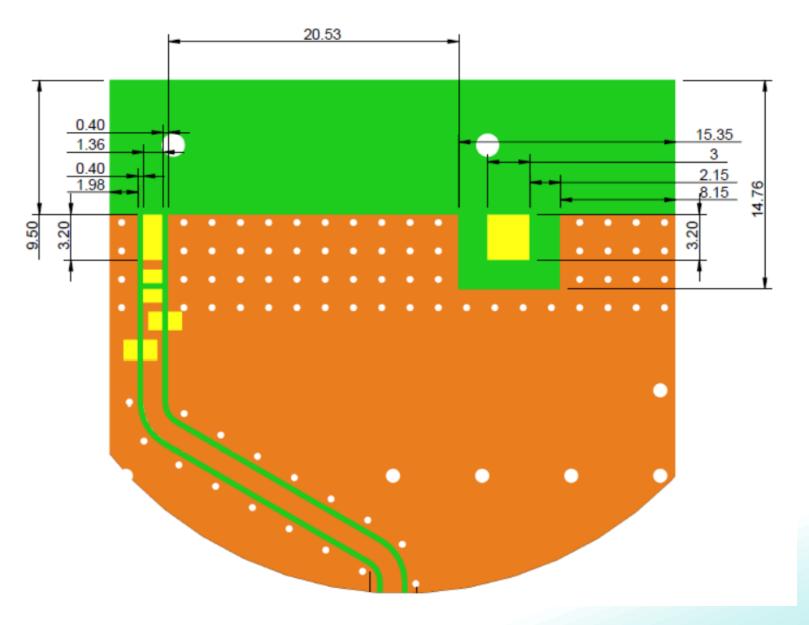
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TEST SETUP

PWB Pad dimension in top copper







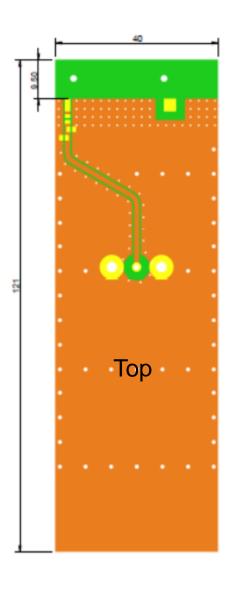
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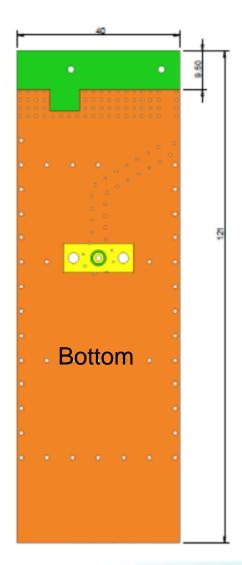
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TEST SETUP

PWB Layout, Pulse PWB size:121x40mm, Thickness 1.0mm, other size boards can be used depending on customer size.







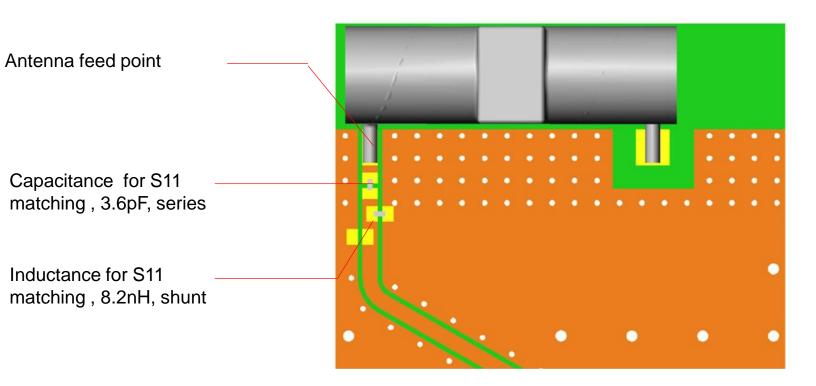
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PWB Layout, Pulse PWB size:121x40mm, Thickness 1.0mm, other size boards can be used depending on customer size.



Note: Exact matching and tuning components value depend on application, board size, cover etc.



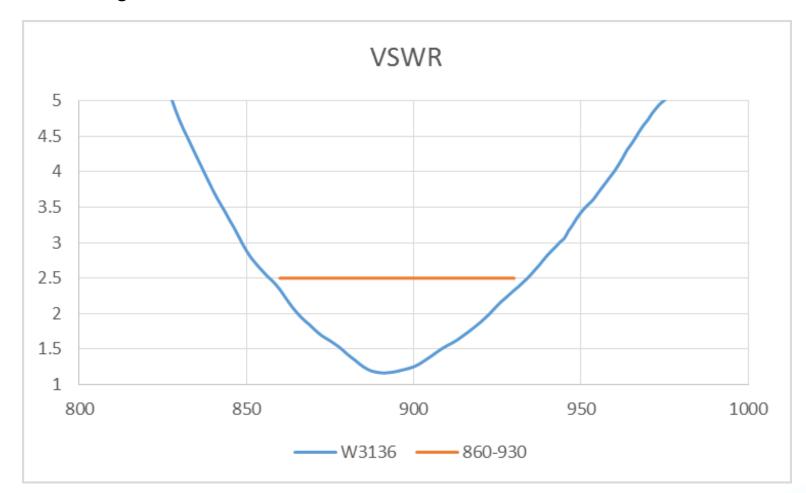
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Measured on the 121x40mm test board with tuning and matching circuit





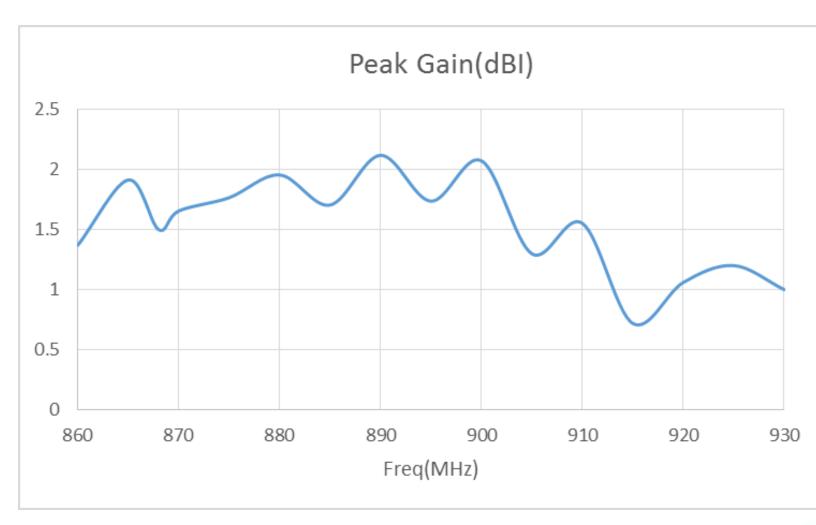


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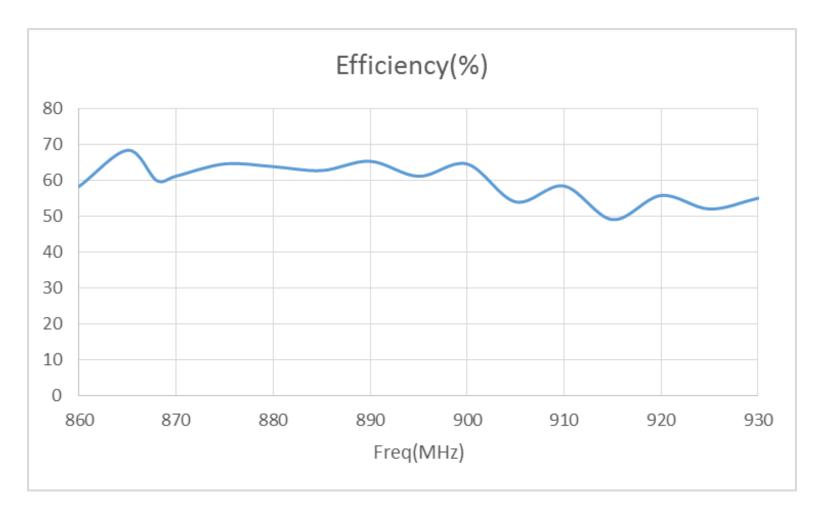


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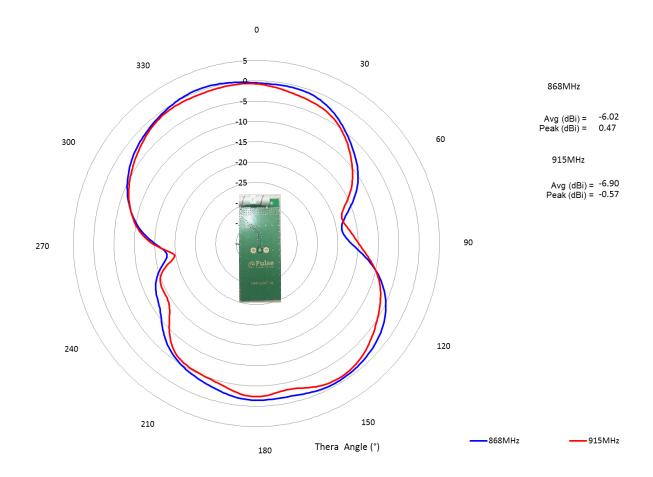
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CHARTS

Typical radiation pattern in free space





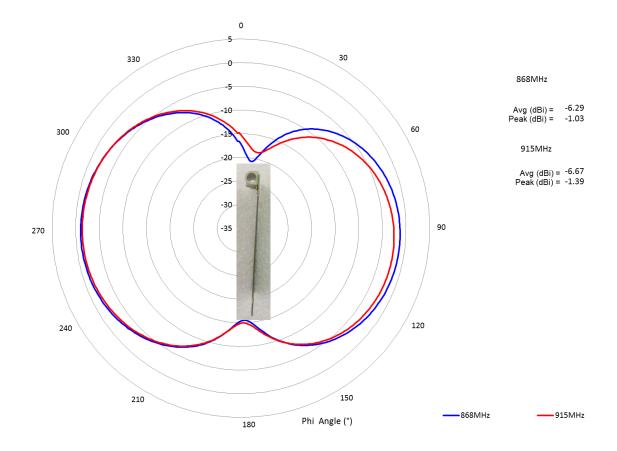
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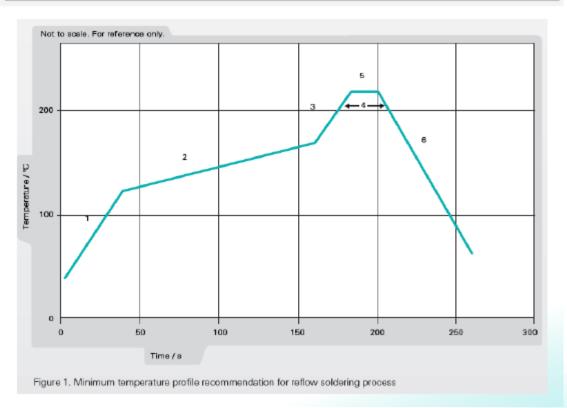
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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 ℃ for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s





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1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 ℃ for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

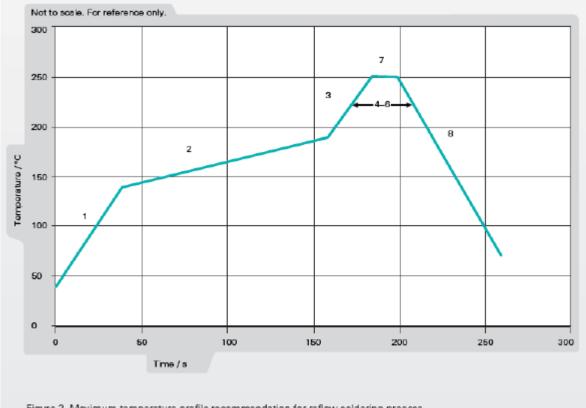


Figure 2. Maximum temperature profile recommendation for reflow soldering process

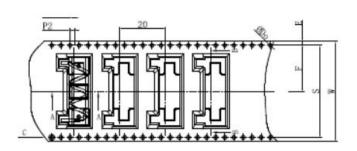


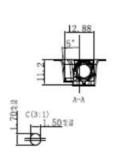
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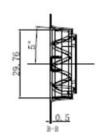
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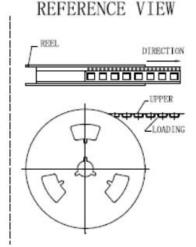
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PACKAGING









All the size design with reference to the EIA - 481 - C - 2003.

6. Loading within 250 mm length maximum curvature is less than



230PCS

13"/44

200PCS

Total PCS

Package Q

Reel

+ / - 0.2 mm. 2. Material specifications: PS black antistatic, thickness of Manufacture Data

> 3.13 inches (100) axis reel package length: 4.6 m. (the front air bag length: 0.33 m, parts packing length: 4 m, after a period of empty packet length: 0.33

4.13 inches (100) axis reel packaging components to the total number of stars: 230, (the front air bag star count: 15, actual packing parts the number: 200, after a period of empty bag star

Total 200 PCS In Reel

Reel Size: 330MM[13INCH]

Total 2 PCS Reel In Package Box

Package Box Size:350x350x120mm